Special Seminar

RESONAC
Chemistry for Change

Dr. Hidenori Abe Seminar

Seminar Topic

Advanced Semiconductor Packaging trend and Resonac's collaboration strategy

DATE & TIME

May 20 (Wed), **2026**
10:30 AM

VENUE

학생복지관
4층 패컬티라운지

102 Student Welfare Building
4F Faculty Lounge

RECRUITMENT INFORMATION BOOTH

Resonac 인사담당자와 상담
(일어 가능자에 한함)

Resonac HR staff will be available before and after the seminar. (Limited to those who can speak Japanese)

Dr. Hidenori Abe
Resonac

CAREER SUMMARY

Title/Position:
CTO for semiconductor materials, Resonac Holdings Corporation
Executive director, Electronics Business Headquarters, Resonac Corporation

Biography

Hidenori Abe is CTO for semiconductor materials and Executive Director of Electronics Business Headquarters at Resonac. He leads R&D and strategy for electronic materials in semiconductors, substrates, and displays.

Previously, Mr. Abe served as the head of the Electronics R&D Center and Packaging Solution Center, where he contributed to advanced packaging development through open innovation. Notably, in 2021, he directed the launch of JOINT2, which concentrates on 2.xD and 3D packaging technologies.

In 2025, he further expanded these efforts through two distinct initiatives: US-JOINT, aimed at international collaboration with a strong focus on the United States, targeting next-generation technology development in partnership with global technology leaders such as GAFAM, and JOINT3, which tackles more advanced and forward-looking packaging and system integration challenges beyond the scope of JOINT2, with a particular emphasis on the development of large-area organic panel-level interposer technologies.

He received a master's degree in chemical engineering from Tokyo Institute of Technology, Japan, and a master's degree in the Executive MBA program from the University of Oxford, UK.

참가 신청 안내

세미나 및 상담 참석을 원하시는 분들은
우측 QR코드를 통해 신청해 주시기 바랍니다.
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